

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7162947

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST

CONVEYING PARTY DATA

Name	Execution Date
BANK OF AMERICA, N.A., AS AGENT	02/07/2022

RECEIVING PARTY DATA

Name:	SMART EMBEDDED COMPUTING, INC.
Street Address:	39870 EUREKA DRIVE
City:	NEWARK
State/Country:	CALIFORNIA
Postal Code:	94560

PROPERTY NUMBERS Total: 30

Property Type	Number
Application Number:	14219051
Application Number:	14490226
Application Number:	13757038
Application Number:	13724952
Application Number:	14251677
Application Number:	15456034
Application Number:	15624319
Application Number:	14023521
Application Number:	15455619
Application Number:	13741710
Application Number:	15616257
Application Number:	14254930
Application Number:	15148271
Application Number:	14490169
Application Number:	14219043
Application Number:	15651023
Application Number:	14140686
Application Number:	14141580
Application Number:	15700561
Application Number:	14141594

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Property Type	Number
Application Number:	14482295
Application Number:	14490186
Application Number:	14219057
Application Number:	10222733
Application Number:	12580449
Application Number:	12580498
Application Number:	13325135
Application Number:	16529919
Application Number:	16667975
Application Number:	16668019

CORRESPONDENCE DATA

Fax Number: (704)444-8847

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 213-457-6624

Email: ksaltrick@mcguirewoods.com

Correspondent Name: MCGUIREWOODS LLP

Address Line 1: 355 S. GRAND AVENUE SUITE 4200

Address Line 2: ATTENTION: Y.LEE, ESQ.

Address Line 4: LOS ANGELES, CALIFORNIA 90071

NAME OF SUBMITTER: YOOJIN LEE

SIGNATURE: /S/ YOOJIN LEE

DATE SIGNED: 02/07/2022

Total Attachments: 4

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**TERMINATION AND RELEASE OF GRANT
OF SECURITY INTEREST IN UNITED STATES PATENTS**

This **TERMINATION AND RELEASE OF GRANT OF SECURITY INTEREST IN UNITED STATES PATENTS** (this "Release Agreement"), dated as of February 7, 2022 is made by **BANK OF AMERICA, N.A.**, a national banking association, as Agent (the "Grantee") in favor of **SMART MODULAR TECHNOLOGIES, INC.**, a California corporation ("Technologies"), **SMART HIGH RELIABILITY SOLUTIONS LLC**, a Delaware limited liability company ("Smart High Reliability"), **SMART EMBEDDED COMPUTING INC.**, a Wisconsin corporation ("Computing"), **PENGUIN COMPUTING INC.**, a California corporation ("Penguin"); and together with **Technologies, Smart High Reliability and Computing**, each, a "Grantor" and collectively, the "Grantors").

WHEREAS, the Grantors and the Grantee are parties to that certain Loan, Guaranty and Security Agreement dated as of December 23, 2020 in which the Grantors delivered to the Grantee that certain Memorandum and Notice of Security Interest in Intellectual Property (the "Memorandum") whereby certain Grantors granted the Grantee a security interest in certain IP Collateral (as that term is defined in the Memorandum) of such Grantors, including the patent and patent registrations listed on **Schedule A** attached hereto (the "Secured Patents") for recordation with the United States Patent and Trademark Office (the "USPTO"); and

WHEREAS, the Memorandum was recorded with respect to the Secured Patents with the Patent Division of USPTO on December 23, 2020 at Reel 54739/Frame 0137; and

WHEREAS, the Obligations secured by said security interest have been paid in full or otherwise satisfied; and

WHEREAS, the Grantee therefore desires to terminate and release its security interest and all of its right, title and interest in each of the IP Collateral, including the Secured Patents, as herein provided.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the Grantee hereby agrees as follows:

1. **Release and Assignment**. The Grantee hereby discharges, terminates and releases the entirety of its security interest in all of the IP Collateral, including the Secured Patents, and the Grantee hereby assigns and transfers to the Grantors, without recourse, all of the Grantee's right, title and interest in and to all of the IP Collateral and each of the Secured Patents, if any, effective as of the date set forth above.

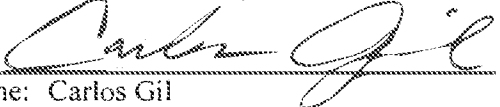
2. **Further Assurances**. The Grantee hereby agrees to execute, acknowledge and deliver all such further instruments and to take all such further actions as may be reasonably requested or are required in order to more fully and effectively carry out the purposes of this Release Agreement at the Grantors' sole cost and expense.

The Grantee hereby agrees that this Release Agreement and all claims shall be governed by the laws of the State of New York, without giving effect to any conflict of law principles except federal laws relating to national banks and Sections 14.13 and 14.15 of the Loan Agreement are hereby incorporated by reference.

[Signature Page Follows]

IN WITNESS WHEREOF, the Grantee has executed this Termination and Release of Grant of Security Interest in United States Patents as of the date written above.

BANK OF AMERICA, N.A.

By: 

Name: Carlos Gil

Title: Senior Vice President

TERMINATION AND RELEASE OF GRANT OF SECURITY INTEREST IN PATENTS
(Smart Modular)
SIGNATURE PAGE

PATENT
REEL: 058913 FRAME: 0100

**SCHEDULE A
TO RELEASE AGREEMENT**

SECURED PATENTS

Owner	Title	Application #	Number
SMART Embedded Computing, Inc.	A RELIABLE, LOW LATENCY HW/SW IPC CHANNEL FOR SAFETY CRITICAL SYSTEM	14/219051	9317359
SMART Embedded Computing, Inc.	ALIGNMENT MECHANISM FOR CABLING TO A CYLINDER HEAD	14/490226	9439312
SMART Embedded Computing, Inc.	AN ELECTRICAL EQUIPMENT CABINET COOLING DEVICE AND A METHOD FOR COOLING AN ELECTRICAL EQUIPMENT CABINET ¹	13/757038	
SMART Embedded Computing, Inc.	CONFIGURABLE COOLING FOR RUGGED ENVIRONMENTS	13/724952	
SMART Embedded Computing, Inc.	DIRECT CONNECT ALGORITHM	14/251677	9367375
SMART Embedded Computing, Inc.	END TO END FPGA DIAGNOSTICS	15/456034	10,338,995
SMART Embedded Computing, Inc.	EXPANSION BOX FOR SAFETY SYSTEMS	15/624319	10,621,031
SMART Embedded Computing, Inc.	EXTENDED HEAT FRAME	14/023521	9414524
SMART Embedded Computing, Inc.	FPGA PACKET STOPPER	15/455619	10,372,579
SMART Embedded Computing, Inc.	INTEGRATED THERMAL INSERTS AND COLD PLATE	13/741710	9713287
SMART Embedded Computing, Inc.	INTEGRATED THERMAL INSERTS AND COLD PLATE	15/616257	10039210
SMART Embedded Computing, Inc.	METHOD AND SYSTEM OF SYNCHRONIZING PROCESSORS TO THE SAME COMPUTATIONAL POINT	14/254930	9348657
SMART Embedded Computing, Inc.	METHOD AND SYSTEM OF SYNCHRONIZING PROCESSORS TO THE SAME COMPUTATIONAL POINT	15/148271	10042812
SMART Embedded Computing, Inc.	MODULAR ELECTRONICS FOR CYLINDERS	14/490169	9288929

¹ Note that in the Memorandum and Notice of Security Interest in Intellectual Property, the title of this patent included a typographical error: "An electrical equipment cabinet cooling device and a method for cooling an electrical equipment cabinet."

Owner	Title	Application #	Number
SMART Embedded Computing, Inc.	OPERATION OF I/O IN A SAFE SYSTEM	14/219043	9747184
SMART Embedded Computing, Inc.	OPERATION OF I/O IN A SAFE SYSTEM	15/651023	10120772
SMART Embedded Computing, Inc.	SAFETY CRITICAL COMPUTER SYSTEM USING COTS COMPONENTS	14/140686	9665447
SMART Embedded Computing, Inc.	SAFETY RELAY BOX SYSTEM	14/141580	9791901
SMART Embedded Computing, Inc.	SIGNAL PAIRING FOR MODULE EXPANSION OF A FAILSAFE COMPUTING SYSTEM	15/700561	10,621,024
SMART Embedded Computing, Inc.	TASK BASED VOTING FOR FAULT-TOLERANT FAIL SAFE COMPUTER SYSTEMS	14/141594	9311212
SMART Embedded Computing, Inc.	TDM DATA AGGREGATION OVER HIGH SPEED SERDES LANE	14/482295	10027600
SMART Embedded Computing, Inc.	THERMAL CONDUCTION TO A CYLINDRICAL SHAFT	14/490186	10327357
SMART Embedded Computing, Inc.	VOTING ARCHITECTURE FOR SAFETY AND MISSION CRITICAL SYSTEMS	14/219057	9497099
SMART Embedded Computing, Inc.	METHOD OF FLOW CONTROL	10/222733	7,274,660
SMART Embedded Computing, Inc.	BLADE CIRCUIT CROSS-CONNECTION ADAPTED FOR PEER-TO-PEER BACKPLANES	12/580449	7,957,138
SMART Embedded Computing, Inc.	SYSTEM AND METHOD FOR SUPPLYING POWER TO ELECTRONICS ENCLOSURES UTILIZING DISTRIBUTED DC POWER ARCHITECTURES	12/580498	8,363,388
SMART Embedded Computing, Inc.	USB RECEPTACLE WITH A RISER AT ITS END	13/325,135	8506324
SMART Embedded Computing, Inc.	UNIVERSAL BRACKET	16/529919	
SMART Embedded Computing, Inc.	CARRIER FOR ONE OR MORE SOLID STATE DRIVES (SSDS)	16/667975	
SMART Embedded Computing, Inc.	PRINTED CIRCUIT BOARD ELECTRICAL CONNECTOR LOCKING VIA THREADED FASTENERS	16/668019	

PATENT

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RECORDED: 02/07/2022